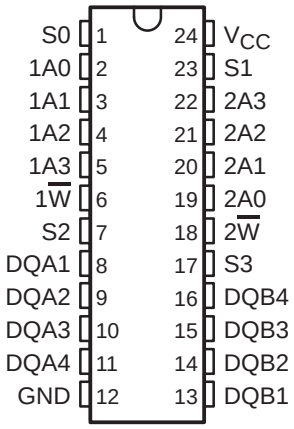
- **3-State Buffer-Type Outputs Drive Bus Lines Directly**
- **Each Register File Has Individual Write-Enable Controls and Address Lines**
- **Designed Specifically for Multibus Architecture and Overlapping File Operations**
- **Prioritized B-Input Port Prevents Write Conflicts During Dual-Input Mode**
- **Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic (NT) 300-mil DIPs**

DW OR NT PACKAGE
(TOP VIEW)



description

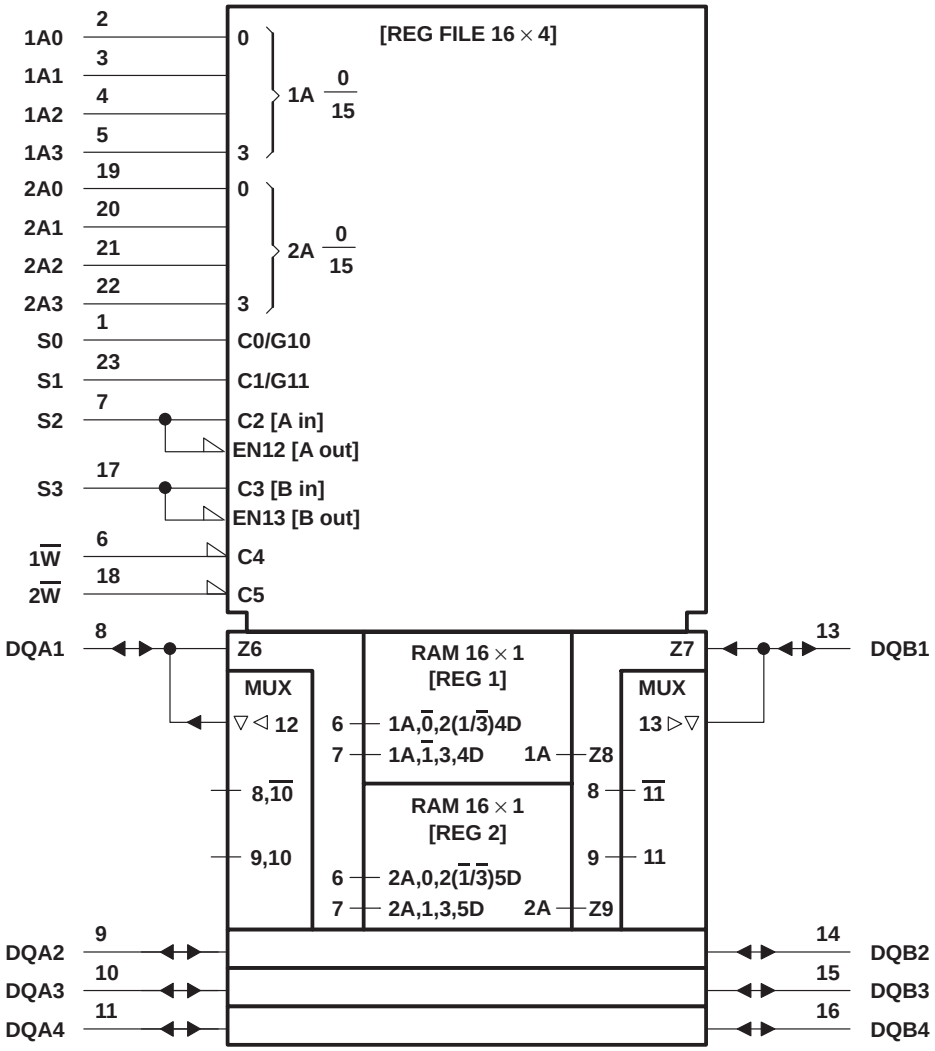
This device features two 16-word by 4-bit register files. Each register file has individual write-enable ($1\overline{W}$, $2\overline{W}$) controls and address lines. This device has two 4-bit data I/O ports (DQA1–DQA4 and DQB1–DQB4). The data I/O ports can output to bus A and bus B, receive input from bus A and bus B, receive input from bus A and output to bus B, or output to bus A and receive input from bus B. To prevent writing conflicts in the dual-input mode, the B-input port takes priority. Two select (S0 and S1) lines control which port has access to which register. S2 determines whether the A ports are in the input or the output modes and S3 does likewise for the B ports. The address lines (1A0–1A3 or 2A0–2A3) are decoded by an internal 1-of-16 decoder to select which register word is to be accessed. All outputs are 3-state buffer-type outputs designed specifically to drive bus lines directly.

The SN74ALS870 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

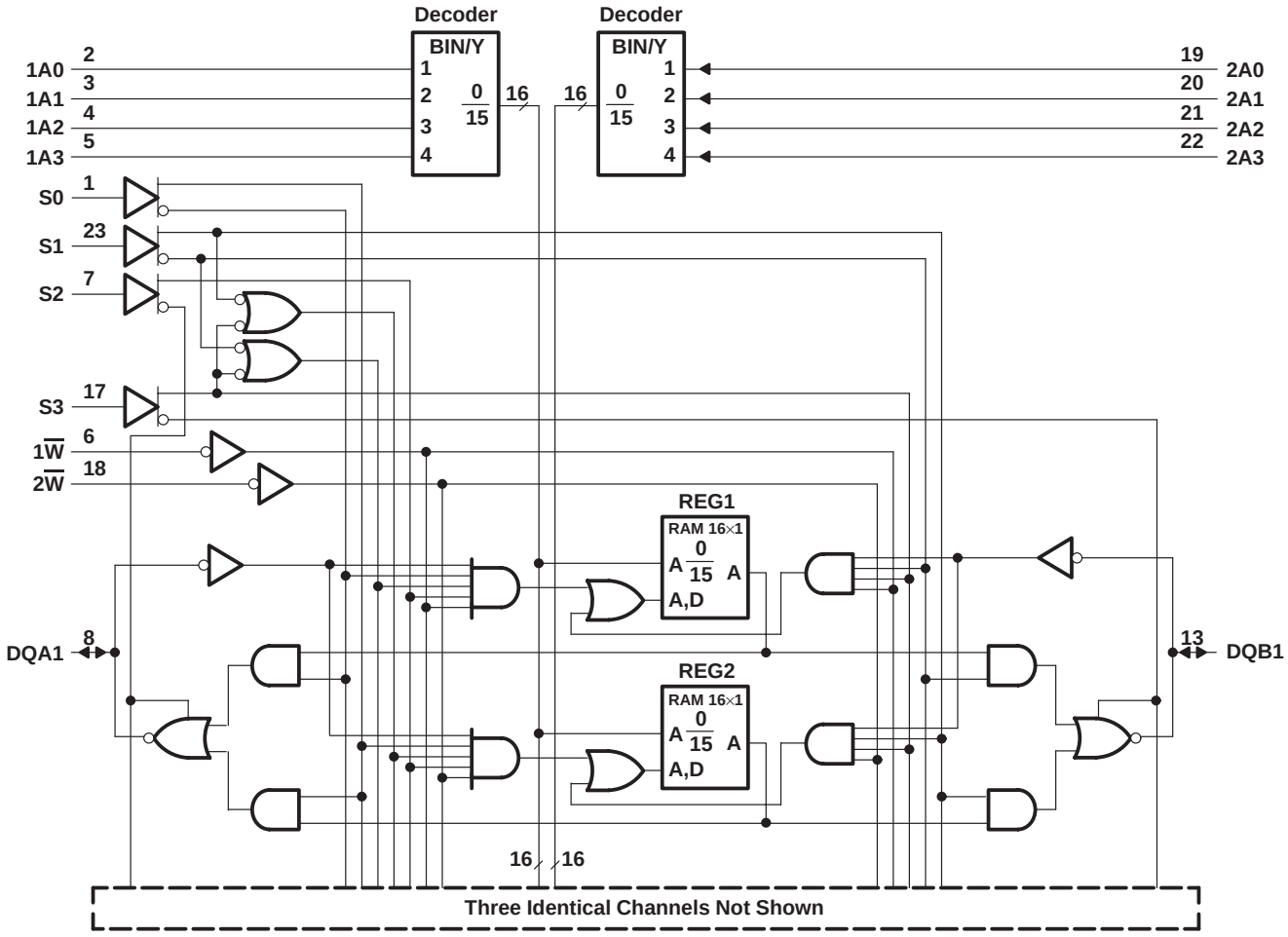
FILE SELECT			INPUT/OUTPUT		
S0	**S1**	**FILE SEL**	**S2**	**S3**	**I/O SEL**
L	L	1R to A, 1R to B	L	L	A out, B out
H	L	2R to A, 1R to B			
L	H	1R to A, 2R to B			
H	H	2R to A, 2R to B			
L	L	A to 1R, 1R to B	H	L	A in, B out
H	L	A to 2R, 1R to B			
L	H	A to 1R, 2R to B			
H	H	A to 2R, 2R to B			
L	L	1R to A, B to 1R	L	H	A out, B in
H	L	2R to A, B to 1R			
L	H	1R to A, B to 2R			
H	H	2R to A, B to 2R			
L	L	B to 1R	H	H	A in, B in
H	L	A to 2R, B to 1R			
L	H	A to 1R, B to 2R			
H	H	B to 2R			

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} . . . . . 7 V
Input voltage, V_I: All inputs . . . . . 7 V
I/O ports . . . . . 5.5 V
Voltage applied to a disabled 3-state output . . . . . 5.5 V
Operating free-air temperature range, T_A . . . . . 0°C to 70°C
Storage temperature range . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		4.5	5	5.5	V
V_{IH}	High-level input voltage		2			V
V_{IL}	Low-level input voltage				0.8	V
I_{OH}	High-level output current				–2.6	mA
I_{OL}	Low-level output current				24	mA
t_w	Pulse duration, write		12			ns
t_{su}	Setup time	Address before write↓	5			ns
		Data before write↑	15			
		Select before write↓	12			
t_h	Hold time	Address before write↓	0			ns
		Data before write↑	0			
		Select before write↓	12			
T_A	Operating free-air temperature		0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2	V
V_{OH}		V_{CC} = 4.5 V to 5.5 V,	I_{OH} = –0.4 mA	V_{CC} –2			V
		V_{CC} = 4.5 V,	I_{OH} = –2.6 mA	2.4	3.2		
V_{OL}		V_{CC} = 4.5 V,	I_{OL} = 24 mA		0.35	0.5	V
I_I	Control inputs	V_{CC} = 5.5 V	V_I = 7 V			0.1	mA
	DQA and DQB ports		V_I = 5.5 V			0.2	
I_{IH}	$1\overline{W}$ and $2\overline{W}$	V_{CC} = 5.5 V,	V_I = 2.7 V			20	µA
	Other control inputs					40	
	DQA and DQB ports‡					50	
I_{IL}	Control inputs	V_{CC} = 5.5 V,	V_I = 0.4 V			–0.2	mA
	DQA and DQB ports‡					–0.2	
I_O§		V_{CC} = 5.5 V,	V_O = 2.25 V	–30		–112	mA
I_{CC}		V_{CC} = 5.5 V			80	110	mA

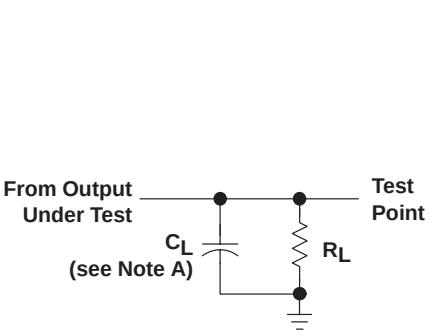
† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.
§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

switching characteristics (see Figure 1)

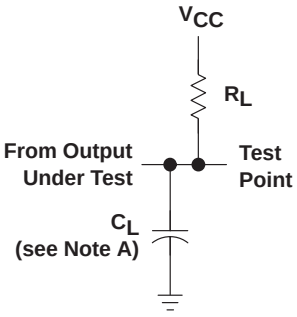
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T_A = MIN to MAX†		UNIT
			MIN	MAX	
$t_{a(A)}$	Any A	Any DQ	3	19	ns
$t_{a(S)}$	S0	Any DQA	3	15	ns
	S1	Any DQB	3	15	
t_{dis}	S2	Any DQA	3	14	ns
	S3	Any DQB	3	14	
t_{en}	S2	Any DQA	3	17	ns
	S3	Any DQB	3	17	
t_{pd}	$\overline{W}$	Any DQ	5	23	ns
	DQA	DQB	5	26	
	DQB	DQA	5	26	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

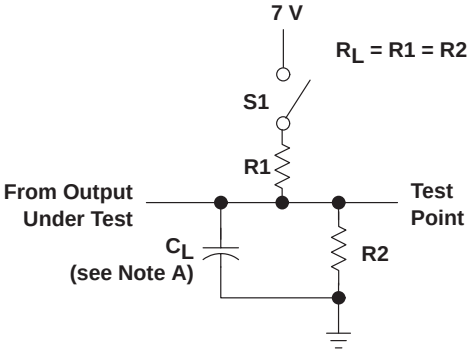
PARAMETER MEASUREMENT INFORMATION
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



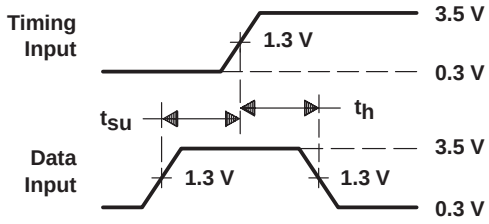
LOAD CIRCUIT FOR
BI-STATE
TOTEM-POLE OUTPUTS



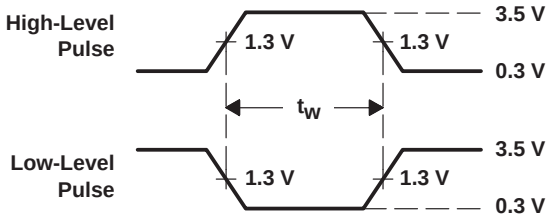
LOAD CIRCUIT
FOR OPEN-COLLECTOR OUTPUTS



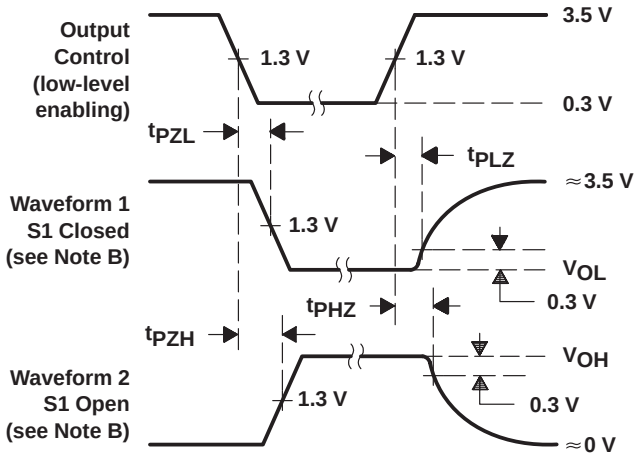
LOAD CIRCUIT
FOR 3-STATE OUTPUTS



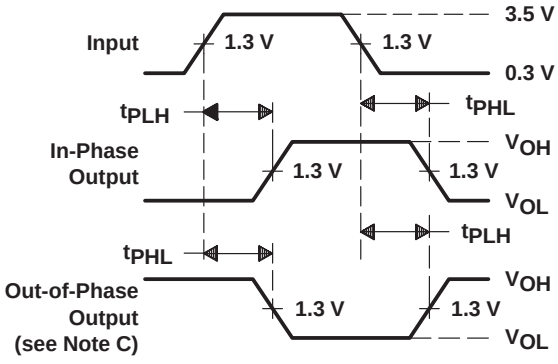
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PULSE DURATIONS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
D. All input pulses have the following characteristics: PRR ≤ 1 MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALS870NT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI	0 to 70	SN74ALS870NT	

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

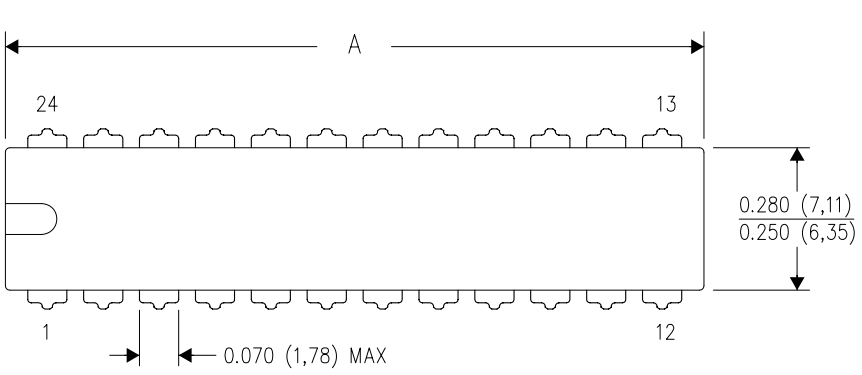
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

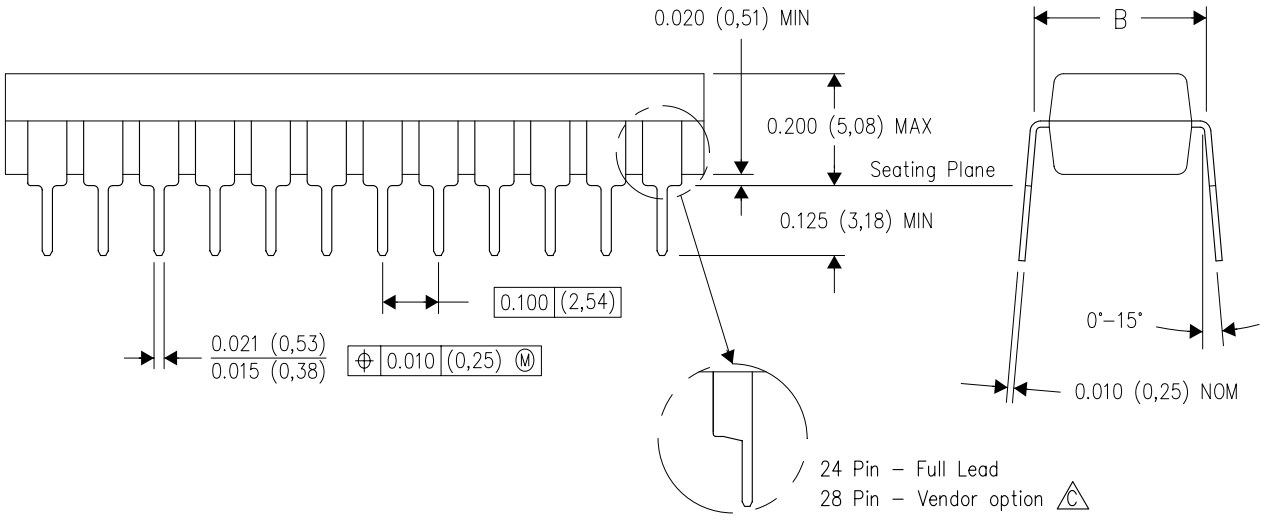
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

NT (R–PDIP–T**) PLASTIC DUAL–IN–LINE PACKAGE

24 PINS SHOWN



DIM \ PINS **	24	28
A MAX	1.260 (32,04)	1.425 (36,20)
A MIN	1.230 (31,24)	1.385 (35,18)
B MAX	0.310 (7,87)	0.315 (8,00)
B MIN	0.290 (7,37)	0.295 (7,49)



4040050/C 04/09

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. The 28 pin end lead shoulder width is a vendor option, either half or full width.

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